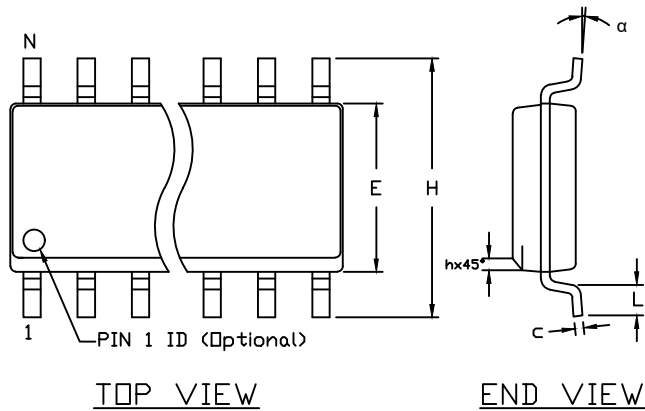




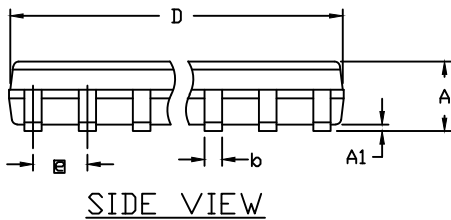
DOCUMENT TYPE: POD
DOCUMENT ID #: 21-0041
REVISION: V-000
DOCUMENT TITLE: PACKAGE OUTLINE, 8L, 14L, 16L SOIC .150
EFFECTIVE DATE: 06/20/2023
EXPIRATION DATE:
CHANGE NUMBER: 1189260
ORIGINATOR: Bernard Go

REASON FOR CHANGE:
Add S8MS+24A



TOP VIEW

END VIEW



SIDE VIEW

COMMON DIMENSIONS						
SYMBOL	INCHES			MM		
	MIN.	TYP.*	MAX.	MIN.	TYP.*	MAX.
A	.053	.061	.069	1.35	1.55	1.75
A1	.004	.007	.010	0.10	0.18	0.25
b	.014	.017	.019	0.35	0.42	0.49
c	.007	.009	.010	0.19	0.22	0.25
E	.150	.154	.157	3.80	3.90	4.00
e	.050 BSC			1.27 BSC		
H	.228	.236	.244	5.80	6.00	6.20
L	.016	.033	.050	0.40	0.84	1.27
alpha	0°	4°	8°	0°	4°	8°
h	0.01	0.015	0.019	0.25	0.38	0.5

* Typical value provided for reference only. This is not a specification.

VARIATION A						
SYMBOL	INCHES			MM		
	MIN.	TYP.*	MAX.	MIN.	TYP.*	MAX.
D	.189	.193	.197	4.80	4.90	5.00
N	8					
MS012	AA					
PKG. CODE	S8+2, S8+2C, S8+4, S8+4C, S8+5, S8+6F, S8+7F, S8+8F, S8+10F, S8+11F, S8+16F, S8+19F, S8+20, S8+21, S8MK+1, S8M+5, S8MS+22, S8+22, S8+23, S8MS+23, S8MS+24, S8MS+24A					

VARIATION B						
SYMBOL	INCHES			MM		
	MIN.	TYP.*	MAX.	MIN.	TYP.*	MAX.
D	.337	.341	.344	8.55	8.65	8.75
N	14					
MS012	AB					
PKG. CODE	S14+1, S14+1C, S14+4, S14+5, S14+6, S14M+4, S14M+5, S14M+6, S14M+7					

VARIATION C						
SYMBOL	INCHES			MM		
	MIN.	TYP.*	MAX.	MIN.	TYP.*	MAX.
D	.386	.390	.394	9.80	9.90	10.00
N	16					
MS012	AC					
PKG. CODE	S16+1, S16+1C, S16+3, S16+5, S16+6, S16+8, S16+7F, S16+9F, S16+10F, S16M+3, S16M+6, S16M+11, S16MS+12					

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.
2. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC # 10-0131.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.15 MM (.006") PER SIDE.
4. LEADS TO BE COPLANAR WITHIN 0.10mm (.004").
5. MEETS JEDEC MS012
6. ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PbfREE (+) PKG. CODES.



TITLE:
PACKAGE OUTLINE,
8L, 14L, 16L SOIC .150 INCH

APPROVAL ALIREZA REZVANI	DOCUMENT CONTROL NO. 21-0041	REV. V	1/1
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REVISION HISTORY

REV	CHANGES MADE	DATE	INIT.
A	ECN #C4214. INITIAL RELEASE INTO DOCUMENT CONTROL	8/10/93	BY
B	ECN #HQ-02-5840. DRAWING UPDATED WITH DALLAS SEMICONDUCTOR LOGO AND INFORMATION.	1/17/03	GP
C	ECN #HQ-10-0025. CHANGED TO THE NEW BORDER/TEMPLATE. ADDED CORRESPONDING PACKAGE CODES. REARRANGED DIMENSIONS	01/15/10	MM
D	ECN HQ-12-2353. Change Template and Add New Package Code	10/10/12	MM
E	ECN HQ-13-2257. ADDED S8MK-1	10/1/13	AG
F	ECN HQ-14-2532. ADDED PKG CODES S8-20 +S8-21	9/29/14	GP
G	CN # 1001170. CN # 1001170. NEW PKGCODES ADDED: S8M-5; S8MS-22	07/28/15	BGRG
H	CN # 1008605 ADD PKG CODE S16MS+12	08/23/16	RG
I	CN# 1015364 ADDED S8-22 TO PKG CODE TABLE	06/06/17	RG
J	CN# 1019495 REV. J ADDED S8-2C TO PKG CODE TABLE	08/31/17	BG
K	CN# 1022122 REV. K. ADDED H DIMENSION	10/16/17	BG
L	CN 1023974. Add notch line on side view	11/16/17	BG
M	CN 1025295 Pin 1 ID is Optional	12/12/17	BG
N	CN 1031351. ADD PKGCODE S8MS-23	04/16/18	BG
O	CN 1035880. Add Typ. values on Common Dimensions Table.	06/01/18	BG
P	CN 1036276. Add Typ. values also on Variations A, B and C tables.	06/07/18	BG
Q	CN 1070436. Add pkg code S8-23.	10/21/19	BG
R	CN 1082663. Add pkgcode S14-1C	04/01/2020	BG
S	CN 1101571. Add S16+1C	10/02/20	BG
T	CN 1104526. Add S8MS+24	10/30/20	BG
U	CN 1112418 Add S8+4C	01/15/21	BG
V	CN 1189260. Add S8MS+24A.	06/20/23	BG

TITLE: PACKAGE OUTLINE, 8L, 14L, 16L SOIC .150 INCH

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